

SFP56

TE Internal #: 2349201-7

zSFP+ Stacked (SFP56), Cage Assembly with Integrated Connector,

.6mm [.018in] Centerline, Signal

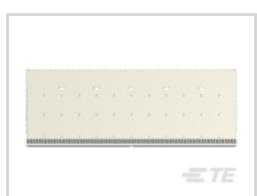
View on TE.com >

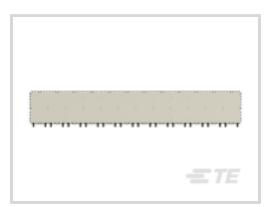


Connectors > Pluggable IO Connectors & Cages > SFP56 Stacked Cage Assembly: EMI Spring











Form Factor: zSFP+ Stacked (SFP56)

Pluggable I/O Product Type: Cage Assembly with Integrated Connector

Centerline (Pitch): .6 mm [.018 in]

Circuit Application: Signal

Operating Temperature Range: -55 – 105 °C [-67 – 221 °F]

All SFP56 Stacked Cage Assembly: EMI Spring (48)

Features

Product Type Features

Product Type Features	
Cage Type	Stacked
Form Factor	zSFP+ Stacked (SFP56)
Pluggable I/O Product Type	Cage Assembly with Integrated Connector
Configuration Features	
Number of Positions	20
Number of Ports	24
Port Matrix Configuration	2 x 12
Electrical Characteristics	
Data Rate (Max)	56 Gb/s
Termination Features	
Termination Method to PCB	Through Hole - Press-Fit

.6 mm[.018 in]

Housing Features

Centerline (Pitch)



Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Pluggable I/O Applications	SFP28
Circuit Application	Signal
Other	
Included Lightpipe	Yes
EMI Containment Feature Type	Internal/External EMI Springs

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

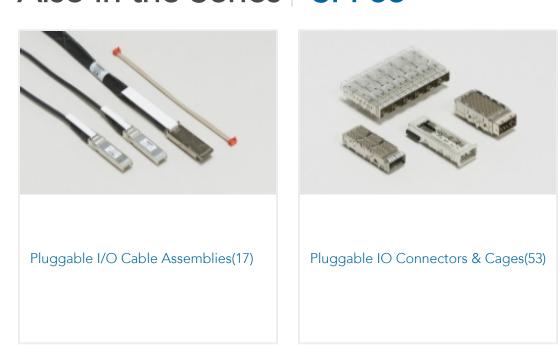
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.



Compatible Parts



Also in the Series | SFP56



Customers Also Bought























Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2349201-7_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2349201-7_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2349201-7_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English